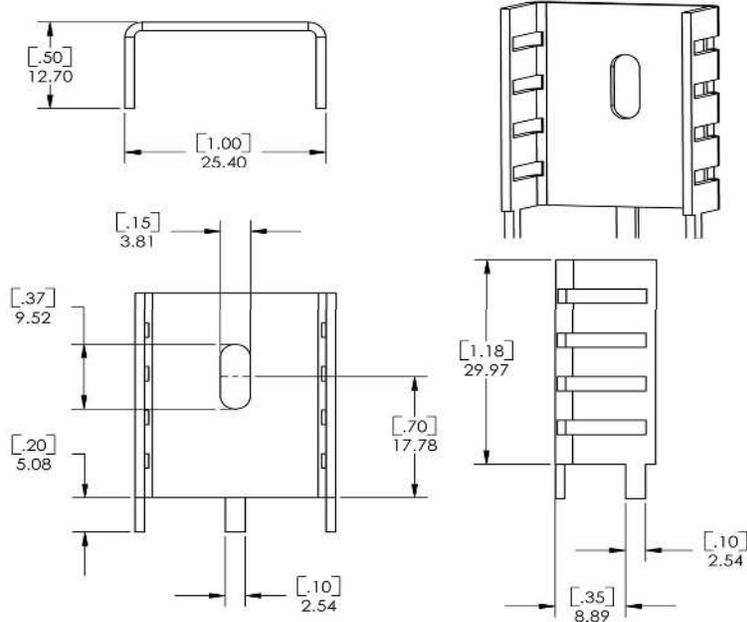
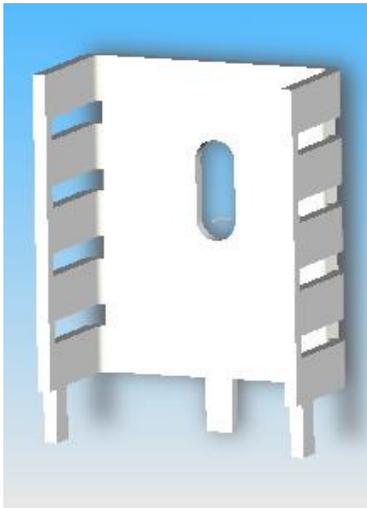


Board Level Heat Sinks



ThermaFlo

P/N: 825600T00000



PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 25.4 x 12.7 x 30.0mm
- Material: Copper, 1.2mm Thick
- Type: Stamped
- Finish: Tin Plate
- Mounting: Solderable Tabs
- Package: Bulk
- Accessories: Hardware & Thermal Interface Material

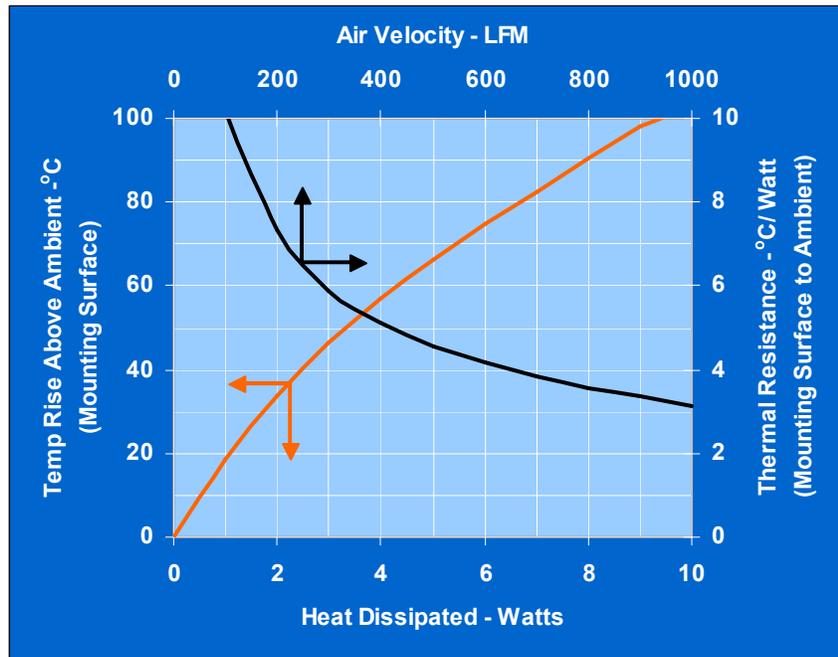
FEATURES & BENEFITS

- Slot for Flexible Device Attachment
- Vertical Mounting via Solderable Tabs
- RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Tabs
- Specialized Body Configurations



TO-220

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